## SPECIFICATION FOR SMT OSCILLATOR MtronPTI P/N M2015S040

## Electrical Specifications:

| Parameter | Symbol | Min. | Typ. | Max. | Units | Conditions |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Frequency of Operation | Fo |  | 1.000000 |  | MHz |  |
| Frequency Stability |  |  |  |  |  |  |
| Frequency Stability | $\Delta \mathrm{F} / \mathrm{F}$ | -100 |  | +100 | ppm |  |
| RF Output |  |  |  |  |  |  |
| Output Type |  | HCMOS |  |  |  |  |
| Output Load |  |  |  | 50 | pF |  |
| Symmetry (duty cycle) | TDC | 40 | 50 | 60 | \% | Ref to $1 / 2 \mathrm{~V} \mathrm{~V}_{\text {d }}$ |
| Logic "1" Level | Vor | $90 \% \mathrm{~V}_{\text {D }}$ |  |  | V | HCMOS load |
| Logic "0" Level | VoL |  |  | $10 \% \mathrm{~V}_{\text {DD }}$ | V | HCMOS load |
| Rise/Fall Time | $\mathrm{T}_{\mathrm{R}} / \mathrm{T}_{\mathrm{F}}$ |  |  | 7 | nS | 10\% to $90 \%$ VDD HCMOS load |
| Tri-state Function |  | $\begin{aligned} & \text { Logic "1" o } \\ & \text { Logic "0" } \\ & \hline \end{aligned}$ | loating |  |  | Lead1: Output Enabled <br> Lead1: Disables Output to Hi-Z |
| Supply Voltage \& Power Consumption |  |  |  |  |  |  |
| Operating Voltage | VDD | 4.5 | 5.0 | 5.5 | V |  |
| Operating Current | ldD |  |  | 20 | mA |  |
| Other Specifications |  |  |  |  |  |  |
| Jitter (Cycle-to-Cycle) |  |  |  | 20 | ps | RMS |

## Environmental \& Mechanical Requirements:

| Operating Temperature | $\mathrm{T}_{\mathrm{A}}$ | -55 |  |  |
| :--- | :--- | :---: | :---: | :---: | :---: |
| Storage Temperature | $\mathrm{T}_{\mathrm{S}}$ | -55 |  |  |
| Mechanical Shock | Per MIL-STD-202, Method 213, Condition $\mathrm{C}(100 \mathrm{~g}$ 's, 6 ms duration, $1 / 2$ sinewave $)$ |  |  |  |
| Vibration | Per MIL-STD-202, Method $201 \& 204(10 \mathrm{~g}$ 's from $10-2000 \mathrm{~Hz})$ |  |  |  |
| Hermeticity | Per MIL-STD-202, Method $112\left(1 \times 10^{-8} \mathrm{~atm} \mathrm{cc} / \mathrm{s}\right.$ of Helium $)$ |  |  |  |
| Solderability | Per EIAJ-STD-002 |  |  |  |
| Max. Soldering Conditions | See solder profile, Figure 1 |  |  |  |
| Package Type | 4 J-lead ceramic. Sn-Pb solder dipped leads. |  |  |  |
| Screening | HiRel Screening required per Hamilton Product Specs. |  |  |  |

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Dimensions, Marking, and Pin Out Information:

| Pad | Function |
| :---: | :--- |
| 1 | Tri-state |
| 2 | Ground $/$ Cover |
| 3 | Output |
| 4 | $+V_{D D}$ |


| Part Marking |  |
| :--- | :--- |
| Line 1 | M2015S040 |
| Line 2 | 1.0000000 M |
| Line 3 | M-TRON yy ww |


| Legend |  |
| :---: | :--- |
| yy | Year |
| ww | Work week |



## SPECIFICATION FOR SMT OSCILLATOR MtronPTI P/N M2015S040



Figure 1

## Datasheet Revision Table:

| Date | Rev. | Author | Details of Revision |
| :---: | :---: | :---: | :--- |
| $01 / 13 / 05$ | 0 | WNJ | Product Part Number changed to track product improvement. Product part number previously was 1517-006 |
| $01-13-05$ | A | WNJ | PCN 10065: Drop In Substrate mounting in the Ceramic package changed to a "sandwich" design to improve <br> CTE issues in product testing and use in HiRel environments. Manual dispensing of epoxy changed to an <br> automated process |
| $02-18-08$ | B | WNJ | Datasheet updated to reflect Hamilton Specification update to Revision P - Rise and Fall time changed to 7ns <br> from 10 |
| $09 / 14 / 17$ | C | MM | Datasheet format update |

